

ABSTRACT

A curable resin film for forming a first protective film on a surface having bumps of a semiconductor wafer by being attached to the surface and being cured, in which a haze (h_1) of a surface of the curable resin film after curing is 50 or lower when the curable resin film is cured by heating at 160°C for one hour or in which a haze (h_2) of a surface of the curable resin film after curing is 50 or lower when the curable resin film is cured by irradiating ultra violet ray in a condition where intensity of illumination is 230 mW/cm² and quantity of light is 510 mJ/cm². A sheet for forming a first protective film includes the curable resin film on one surface of a first supporting sheet.